**N-Ch MOSFET** 

# **General Description**

The WSF60100 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF60100 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

#### **Product Summery**

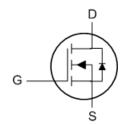
BVDSS	RDSON	ID
60V	5.3mΩ	98A

## **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

# **TO-252 Pin Configuration**





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	100	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	80	А
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	14	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	11	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	285	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	182	mJ
I <sub>AS</sub>	Avalanche Current	60	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	150	W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	2.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	℃
$T_J$	Operating Junction Temperature Range -55 to 175		$^{\circ}$

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.057		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		5.3	6.4	0
R <sub>DS(ON)</sub>		V <sub>GS</sub> =10V , I <sub>D</sub> =20A ,TJ=125℃		8.4	10.5	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/   -250\	2	3	4	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$-V_{GS}=V_{DS}$ , $I_D=250uA$		-5.68		mV/℃
	Drain Source Leekage Current	$V_{DS}$ =48V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	- uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		75		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		0.65	1.0	Ω
$Q_{g}$	Total Gate Charge (4.5V)			54	75	
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =48V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		23	35	nC
Q <sub>gd</sub>	Gate-Drain Charge			18	28	
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =30V , $V_{GS}$ =10V , $R_{G}$ =3 $\Omega$ , RL=1.5 $\Omega$ .		19	24.4	
Tr	Rise Time			22	30	
T <sub>d(off)</sub>	Turn-Off Delay Time			33	32	ns
T <sub>f</sub>	Fall Time			6	10	
C <sub>iss</sub>	Input Capacitance			4055	5500	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		346	503	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			18	120	

### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =60A	100			mJ

### **Diode Characteristics**

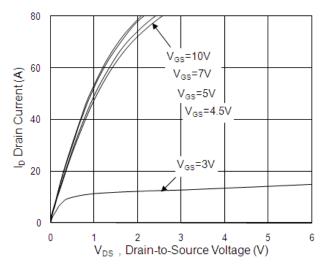
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			46	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				60	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=20A ,dI/dt=500A/μs,Tյ=25℃		26		nS
Q <sub>rr</sub>	Reverse Recovery Charge			126		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =60A
- 4. The power dissipation is limited by 150 °C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

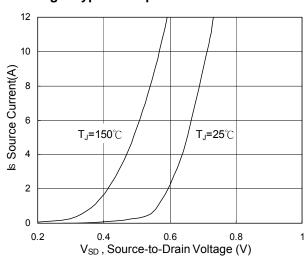


Fig.3 Forward Characteristics of Reverse

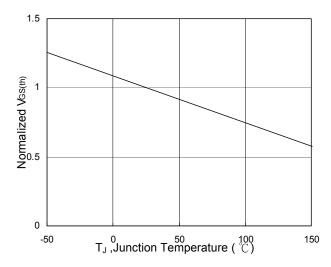


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

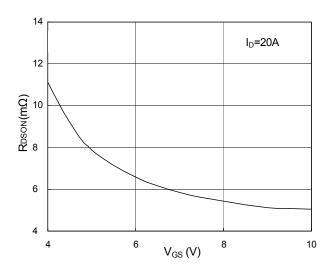


Fig.2 On-Resistance v.s Gate-Source

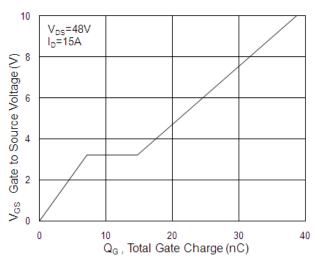


Fig.4 Gate-Charge Characteristics

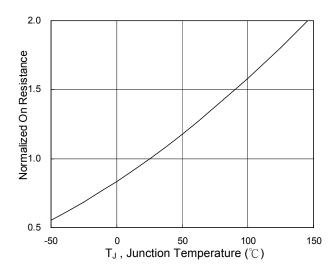
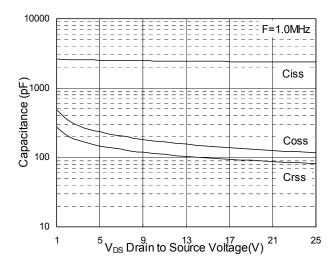


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>







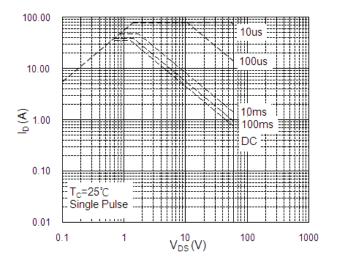


Fig.7 Capacitance

Fig.8 Safe Operating Area

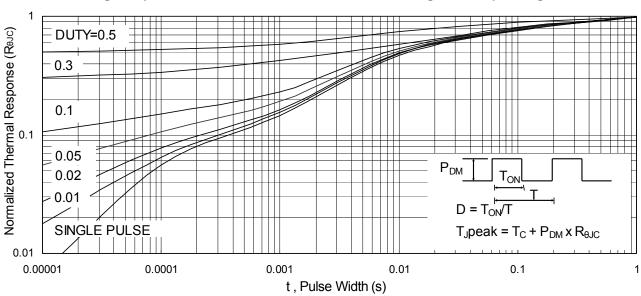


Fig.9 Normalized Maximum Transient Thermal Impedance

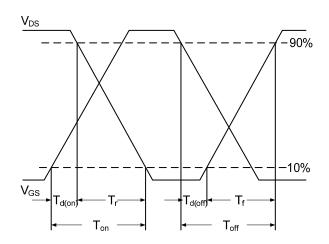


Fig.10 Switching Time Waveform

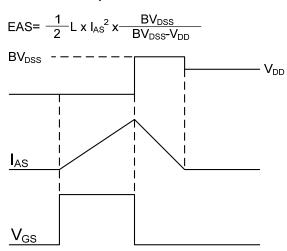


Fig.11 Unclamped Inductive Switching Waveform



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